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# BrewerBOND® 510

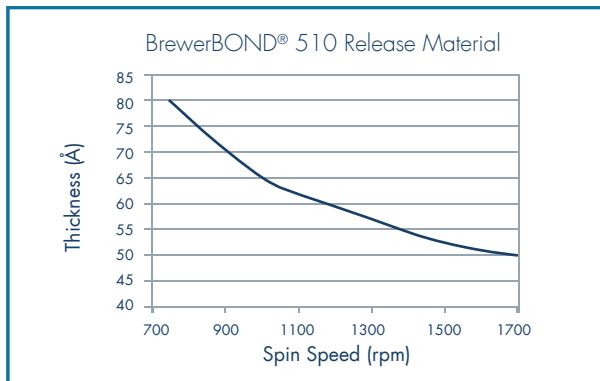
Temporary wafer bonding release material for mechanical debonding applications

## KEY MARKET SECTORS

- 3-D wafer-level packaging
- MEMS
- Compound semiconductor

## PROCESSING

### Spin Speed Curve (SSC)



Metrology tool: Ellipsometer (refractive index [nf] set at 1.2)

$T_d$  (TGA\*) = 280°C

\* IPC-TM-650 2.4.24.6 (2% Loss)

### Material Properties

n at 633 nm 1.230

k at 633 nm 1.003

Contact Angle (with water at room temperature)

104° ± 2°

## BENEFITS

- Compatible with 250°C - 300°C bonding materials
- Simple application on carrier
- Lower cost of ownership with carrier reuse
- Carrier rework by RCA clean or ash
- Low-force separation

### BrewerBOND® 510 Release Material Coating Parameters (8" substrate)

Static dispense in center of substrate

Spin Speed See spin speed curve provided for thickness target

Acceleration 10,000 rpm/s

Spin Time 30 s

### Hot Plate Baking Process

Proximity Bake 205°C for 60 s

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